

**ABSTRACT:**

Wave soldering machine and method of adjusting and automatically controlling the height of a solder wave.

The invention relates to a wave soldering machine with at least one device for generating at least one solder wave (10a) consisting of liquid solder (10) for wetting assembled units (22) which are conducted over the solder wave (10a). To achieve a reproducible adjustment and control of the wave height (24), it is proposed to mount at least  
5 one temperature-compensated pressure sensor (18) in the transport path of the solder (10), preferably in the immediate vicinity of the nozzle opening (13).

Figure.

This Sheet Has Been Replaced

